

General Description

The MAX9381 differential data, differential clock D flipflop is pin compatible with the ON Semiconductor MC100EP52, with the added benefit of a wider supplyvoltage range from 2.25V to 5.5V and 25% lower supply current. Data enters the master part of the flip-flop when the clock is low and is transferred to the outputs upon a positive transition of the clock. Interchanging the clock inputs allows the part to be used as a negative edge-triggered device. The MAX9381 utilizes input clamping circuits that ensure the stability of the outputs when the inputs are left open or at VEE.

The MAX9381 is offered in an 8-pin SO package and the smaller 8-pin µMAX package.

Applications

Precision Clock and Data Distribution

Central Office

DSLAM

DLC

Base Station

ATE

Features

- **♦ 3.0GHz Guaranteed Operating Clock Frequency**
- ♦ 0.2psRMS Added Random Jitter
- ♦ 328ps Typical Propagation Delay
- ♦ PECL Operation from V_{CC} = 2.25V to 5.5V with VEE = 0V
- ♦ ECL Operation from VEE = -2.25V to -5.5V with Vcc = 0V
- ♦ Input Safety Clamps Ensure Output Stability when Inputs are Open or at VEE
- ♦ ±2kV ESD Protection (Human Body Model)

Ordering Information

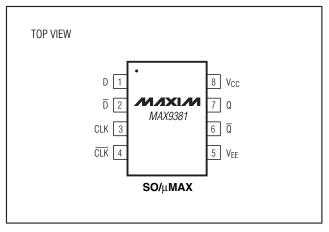
PART	TEMP RANGE	PIN-PACKAGE
MAX9381ESA	-40°C to +85°C	8 SO
MAX9381EUA*	-40°C to +85°C	8 µMAX

^{*}Future product—contact factory for availability.

Functional Diagram

NIXINI MAX9381 -Vcc Q CLK -- V_{FF}

Pin Configuration



MIXIM

Maxim Integrated Products 1

ABSOLUTE MAXIMUM RATINGS

$\begin{array}{cccccccccccccccccccccccccccccccccccc$
Output Current (Q, \overline{Q})
Continuous50mA
Surge100mA
Junction-to-Ambient Thermal Resistance in Still Air
8-Pin μMAX+221°C/W
8-Pin SO+170°C/W
Maximum Continuous Power Dissipation
8-Pin µMAX (derate 4.5mW/°C above +70°C)362mW
8-Pin SO (derate 5.9mW/°C above +70°C)471mW

Junction-to-Ambient Thermal Resista 500LFPM Airflow	nce with
8-Pin μMAX	+155°C/W
8-Pin SO	+99°C/W
Junction-to-Case Thermal Resistance	
8-Pin μMAX	+39°C/W
8-Pin SO	+40°C/W
Operating Temperature Range	40°C to +85°C
Junction Temperature	+150°C
Storage Temperature Range	
ESD Protection	
Human Body Model	±2kV
Soldering Temperature (10s)	+300°C

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

DC ELECTRICAL CHARACTERISTICS

 $(V_{CC} - V_{EE} = 2.25 V \text{ to } 5.5 V \text{ (T}_{A} = +25 ^{\circ}\text{C to } +85 ^{\circ}\text{C)}, V_{CC} - V_{EE} = 2.375 V \text{ to } 5.5 V \text{ (T}_{A} = -40 ^{\circ}\text{C to } +25 ^{\circ}\text{C)}, \text{ outputs terminated with } 50\Omega \pm 1\% \text{ to } V_{CC} - 2.0 V, \text{ unless otherwise noted.}$ Typical values are at $V_{CC} - V_{EE} = 3.3 V, V_{IHD} = V_{CC} - 1.0 V, V_{ILD} = V_{CC} - 1.5 V, \text{ unless otherwise noted.})$ (Notes 1, 2, and 3)

PARAMETER SYMB		CONDITIONS		-40°C			+25°C			+85°C			UNITS
PARAMETER	SYMBOL	COMPITIONS		MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	UNITS
INPUTS (D, \overline{D} , CL	K, CLK)												
Differential Input High Voltage	V _{IHD}	Figure 1		V _{EE} + 1.2		V _C C	V _{EE} + 1.2		V _C C	V _{EE} + 1.2		V _C C	V
Differential Input Low Voltage	VILD	Figure 1		VEE		V _{CC} - 0.15	VEE		V _{CC} - 0.15	VEE		V _{CC} - 0.15	V
Differential Input Voltage	VID	Figure 1	V _{CC} - V _{EE} < 3.0V	0.15		V _{CC} -	0.15		V _{CC} -	0.15		V _{CC} -	- V
			V _{CC} - V _{EE} ≥ 3.0V	0.15		3.0	0.15		3.0	0.15		3.0	
Single-Ended Input Current	I _{IH} , I _{IL}	D, D, CLK, or CLK = V _{IHD} or V _{ILD}		-10		+200	-10		+200	-10		+200	μA
OUTPUTS (Q, \overline{Q})													•
Output High Voltage	VoH	Figure 1		V _{CC} - 1.145		V _{CC} - 0.895	V _{CC} - 1.145		V _{CC} - 0.895	V _{CC} - 1.145		V _{CC} - 0.895	V
Output Low Voltage	VoL	Figure 1		V _{CC} - 1.945		V _{CC} - 1.695	V _{CC} - 1.945		V _{CC} - 1.695	V _{CC} - 1.945		V _{CC} - 1.695	V
Differential Output Voltage	V _{OD}	V _{OH} - V _{OL} , Figure 1		550			550			550			mV
POWER SUPPLY													
Power-Supply Current (Note 4)	IEE				17	35		20	35		22	35	mA

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AC ELECTRICAL CHARACTERISTICS

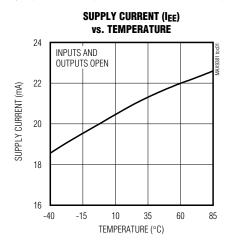
 $(V_{CC} - V_{EE} = 2.25 V \ to \ 5.5 V \ (T_A = +25 ^{\circ}C \ to \ +85 ^{\circ}C), \ V_{CC} - V_{EE} = 2.375 V \ to \ 5.5 V \ (T_A = -40 ^{\circ}C \ to \ +25 ^{\circ}C), \ outputs \ terminated \ with \ 50 \Omega \ \pm 1\% \ to \ V_{CC} - 2.0 V, \ f_{CLK} \le 3.0 GHz, \ input \ transition \ time = 125 ps (20\% \ to \ 80\%), \ V_{IHD} = V_{EE} + 1.2 V \ to \ V_{CC}, \ V_{ILD} = V_{EE} \ to \ V_{CC} - 0.15 V, \ V_{IHD} = V_{EE} \ to \ V_{CC} - 0.15 V, \ V_{IHD} = V_{CC} - 1.5 V, \ V_{IHD} = V_{CC} -$

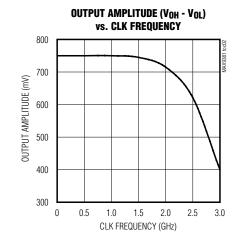
PARAMETER	SYMBOL	CONDITIONS	-40°C			+25°C			+85°C			UNITS
PARAMETER SYMBUL		CONDITIONS	MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	UNITS
Propagation Delay CLK, CLK to Q, Q	tphl tplh	Figure 2			370		328	405			490	ps
Maximum Clock Frequency	fCLKMAX	V _{OD} ≥ 300mV	3.0			3.0			3.0			GHz
Setup Time	ts	Figure 2	100			100			100			ps
Hold Time	tH	Figure 2	50			50			50			ps
Added Random Jitter (Note 6)	t _{RJ}			0.2	0.8		0.2	0.8		0.2	0.8	ps (RMS)
Differential Output Rise/Fall Time	t _R /t _F	20% to 80%, Figure 2	70	120	170	80	120	180	90	120	200	ps

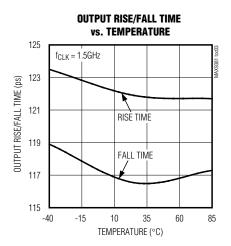
- **Note 1:** Measurements are made with the device in thermal equilibrium.
- Note 2: Current into a pin is defined as positive. Current out of a pin is defined as negative.
- Note 3: DC parameters are production tested at +25°C. DC limits are guaranteed by design and characterization over the full operating temperature range.
- Note 4: All pins floating except V_{CC} and V_{EE}.
- Note 5: Guaranteed by design and characterization, and are not production tested. Limits are set to ±6 sigma.
- Note 6: Device jitter added to the input clock.

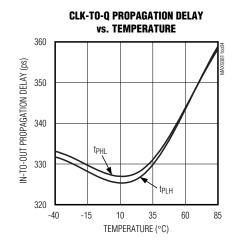
Typical Operating Characteristics

 $(V_{CC} - V_{EE} = 3.3V, outputs loaded with 50\Omega \pm 1\% to V_{CC} - 2V, V_{IH} = V_{CC} - 1V, V_{IL} = V_{CC} - 1.5V, f_{CLK} = 3GHz, f_D = f_{CLK}/2 input transition time = 125ps (20% to 80%), unless otherwise noted.)$









Pin Description

PIN	NAME	FUNCTION
1	D	Noninverting D Input to the Flip-Flop. Internally pulled down with a 75k Ω resistor to V _{EE} .
2	D	Inverting D Input to the Flip-Flop. Internally pulled down with a 75k Ω resistor to V _{EE} .
3	CLK	Noninverting Clock Input to the Flip-Flop. Internally pulled down with a 75k Ω resistor to V _{EE} .
4	CLK	Inverting Clock Input to the Flip-Flop. Internally pulled down with a 75k Ω resistor to V _{EE} .
5	VEE	Negative Supply
6	Q	Inverting Q Output from the Flip-Flop. Terminate with a 50Ω resistor to V_{CC} - 2V or equivalent.
7	Q	Noninverting Q Output from the Flip-Flop. Terminate with a 50Ω resistor to V_{CC} - 2V or equivalent.
8	Vcc	Positive Supply. Bypass from V _{CC} to V _{EE} with 0.1µF and 0.01µF ceramic capacitors. Place the capacitors as close to the device as possible with the smaller value capacitor closest to the device.

Detailed Description

The MAX9381 D flip-flop transfers the logic level at the D input to the Q output on a rising edge transition of the clock, provided the minimum setup and hold times are met. By interchanging the CLK and CLK inputs, the flip-flop functions as a falling-edge triggered flip-flop.

The input signals (D, \overline{D} and CLK, $\overline{\text{CLK}}$) are differential and have a maximum differential input voltage of 3.0V or V_{CC} - V_{EE}, whichever is less. To ensure that the outputs remain stable when the inputs are left open, each of the inputs is driven low by a 75k Ω bias resistor connected to V_{EE}. If the D and \overline{D} inputs are left open or at V_{EE}, the output is guaranteed to be a differential low on the next low-to-high transition of the clock. If the CLK and $\overline{\text{CLK}}$ inputs are left open or at V_{EE}, the outputs remain unchanged (Table 1). Terminate the outputs (Q, $\overline{\Omega}$) through 50 Ω to V_{CC} - 2V or an equivalent Thevenin termination (see the *Output Termination* section).

ECL/PECL Operation

Output levels are referenced to $V_{\rm CC}$ and are considered PECL or ECL, depending on the level of the $V_{\rm CC}$

Table 1. Truth Table*

$\overline{D}, \overline{\overline{D}}$	CLK, CLK	Q, \overline{Q}			
L	↑	L			
Н	1	Н			
Open or V _{EE}	1	L,			
Χ	Open or VEE	No change			

*Where logic states are differential, ↑ is a low-to-high transition and X signifies a don't care state.

supply. With V_{CC} connected to a positive supply and V_{EE} connected to GND, the outputs are PECL. The outputs are ECL when V_{CC} is connected to GND and V_{EE} is connected to a negative supply.

Applications Information

T Flip-Flop

The MAX9381 can be configured as a T flip-flop by connecting Q to \overline{D} and \overline{Q} to D. This configuration provides an output at half the frequency of the clock. The maximum operating frequency is determined by the sum of the setup time, the propagation delay of the

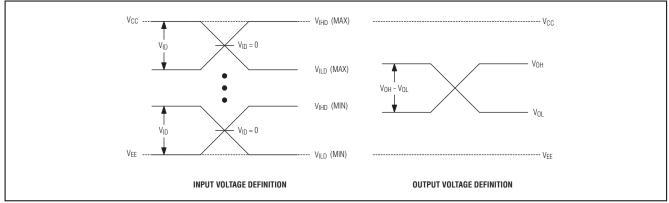


Figure 1. Input and Output Voltage Definitions

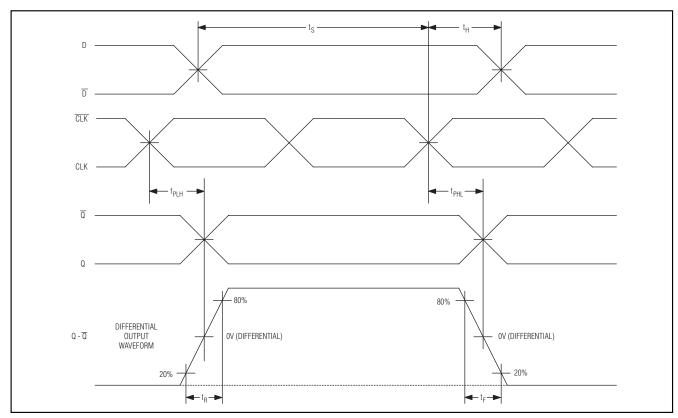


Figure 2. CLK-to-Q Propagation Delay and Transition Timing Diagram

device and any added delay by circuit board traces. The minimum supply voltage is 2.375V and is determined by input and output voltage range.

Output Termination

Terminate the outputs through 50Ω to VCC - 2V or use equivalent Thevenin terminations. Terminate each Q and \overline{Q} outputs with identical termination on each for the lowest output distortion. When a single-ended signal is taken from the differential output, terminate both Q and \overline{Q} .

Ensure that output currents do not exceed the current limits as specified in the *Absolute Maximum Ratings* table. Under all operating conditions, the device's total thermal limits should be observed.

Power-Supply Bypassing

Bypass VCC to VEE with high-frequency surface-mount ceramic 0.1µF and 0.01µF capacitors. Place the capacitors as close to the device as possible with the 0.01µF capacitor closest to the device pins.

Use multiple vias when connecting the bypass capacitors to ground. This reduces trace inductance, which lowers power-supply bounce when drawing high transient currents.

Circuit Board Traces

Circuit board trace layout is very important to maintain the signal integrity of high-speed differential signals. Maintaining integrity is accomplished in part by reducing signal reflections and skew, and increasing common-mode noise immunity.

Signal reflections are caused by discontinuities in the 50Ω characteristic impedance of the traces. Avoid discontinuities by maintaining the distance between differential traces, not using sharp corners, or using vias. Maintaining distance between the traces also increases common-mode noise immunity. Reducing signal skew is accomplished by matching the electrical length of the differential traces.

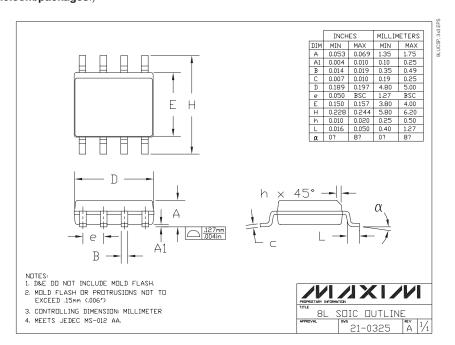
Chip Information

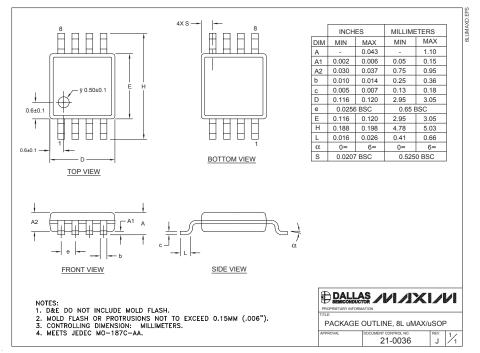
TRANSISTOR COUNT: 375

PROCESS: Bipolar

Package Information

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information, go to **www.maxim-ic.com/packages**.)





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